ABSTRACT

HYPER THERMALLY ENHANCED SEMICONDUCTOR PACKAGE SYSTEM COMPRISING HEAT SLUGS ON OPPOSITE SURFACES OF A SEMICONDUCTOR CHIP

A semiconductor package system is provided including mounting a semiconductor chip to a substrate having a substrate opening. A first heat slug is attached to a first surface of the semiconductor chip at least partially encapsulating the semiconductor chip. A second heat slug is attached to the second surface of the semiconductor chip through the substrate opening. (FIG. 1)